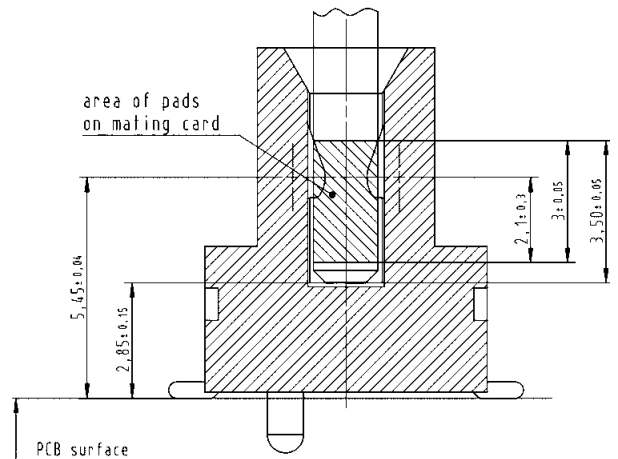
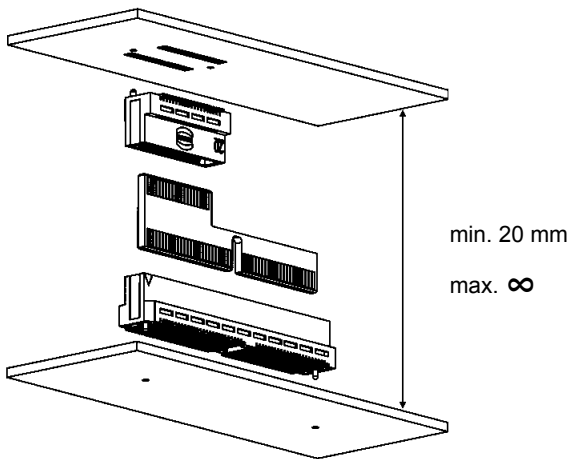


Contact spacing	: 0.8 mm
Working current	: 1.7 A at 80 °C ambient
Test voltage	: 600 V AC
Mating cycles	: 200
Number of contacts	: 40, 100
Mating card thickness	: 1.6 + 0.1 mm
Operating temperature	: -55 °C up to +125 °C
Max processing temperature	: 230 °C for 60 sec. or 260 °C for 20 sec.
ROHS-compliance	: yes

## Materials

Mouldings	: LCP, glass-fibre filled, UL 94-V0
Contacts	: Copper alloy with Ni plating
Contact surface	
Contact zone	: Pd/Ni plating with Au flash
Termination zone	: Sn/Ni plating

## Board dimensions



## Recommended mating card layout

